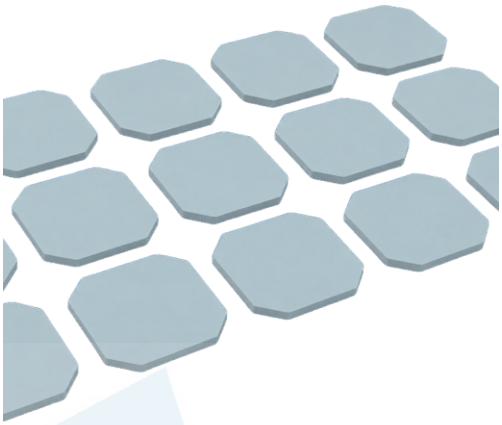
SF-76

Ultra-Soft Non-Silicone Thermal Pad for Low-Stress Applications

Product Description



SF-76 is an ultra-soft non-silicone thermal interface pad engineered for applications requiring low assembly stress, excellent compressibility, and reliable thermal performance. Featuring 6 W/m·K thermal conductivity and a soft Shore OO 35 hardness, SF-76 provides exceptional surface conformability and gap-filling capability for delicate electronic assemblies and uneven component interfaces.

Unlike conventional non-silicone thermal pads that are typically rigid and difficult to compress, SF-76 maintains excellent flexibility and cushioning characteristics while delivering stable thermal performance.

The SF series eliminates the risk of siloxane migration and outgassing associated with silicone-based thermal materials, making SF-76 an ideal thermal solution for sensitive electronic, optical, networking, and industrial applications requiring clean and low-stress thermal interfaces.

FEATURES & BENEFITS

- **Ultra-Soft Non-Silicone Design:**

Combines siloxane-free reliability with exceptional softness and flexibility.

- **Low-Stress Thermal Interface:**

Shore OO 35 hardness minimizes mechanical stress on delicate components.

- **Excellent Compressibility:**

Highly conformable structure improves contact across uneven surfaces.

- **Reliable Thermal Performance:**

6 W/m·K conductivity enables efficient heat dissipation for electronic devices.

- **Enhanced Gap-Filling Capability:**

Provides effective interface contact in low-pressure assembly environments.

- **Clean & Stable Operation:**

Ideal for contamination-sensitive optical and electronic systems.

PROPERTY	SF-76	TEST METHOD
Construction	Ceramic Filled polyolefin elastomer	N/A
Color	Blue	Visual
Density	3.2 g/cc	ASTM D792
Thickness Range	0.3mm~10.0mm	N/A
Thermal Conductivity	6.0 W/m-K	Hot Disk
Rth at 1mm,10psi	0.2 °C-in^2/W	ASTM D5470
Hardness Shore OO	35	ASTM D2240
Dielectric Constant@1MHz	7 @1MHz	ASTM D150
Dielectric Strength	>8 KVac/mm	
Volume Resistivity	10^{14}Ω-cm	ASTM D257
Temperature Range	-40°C to 150°C	VOT Test Method
Flammability Rating	V-0	UL 94

Typical Applications

- AI & High-Performance Computing
- Optical Modules & Transceivers
- Networking Equipment
- SSD & Memory Modules
- Industrial Electronics
- Low-Pressure Electronic Assemblies
- GPU / CPU Thermal Interfaces
- Sensitive Electronic Components

Storage Conditions

- Storage Temperature: 15°C to 35°C, RH <50%
- Shelf Life:12 months under above conditions

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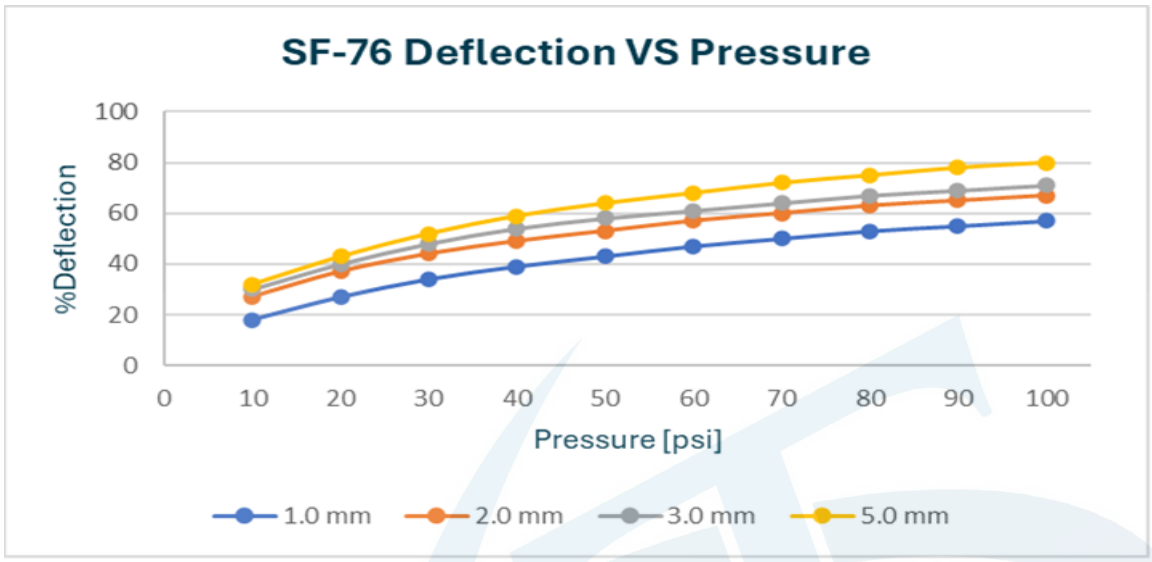

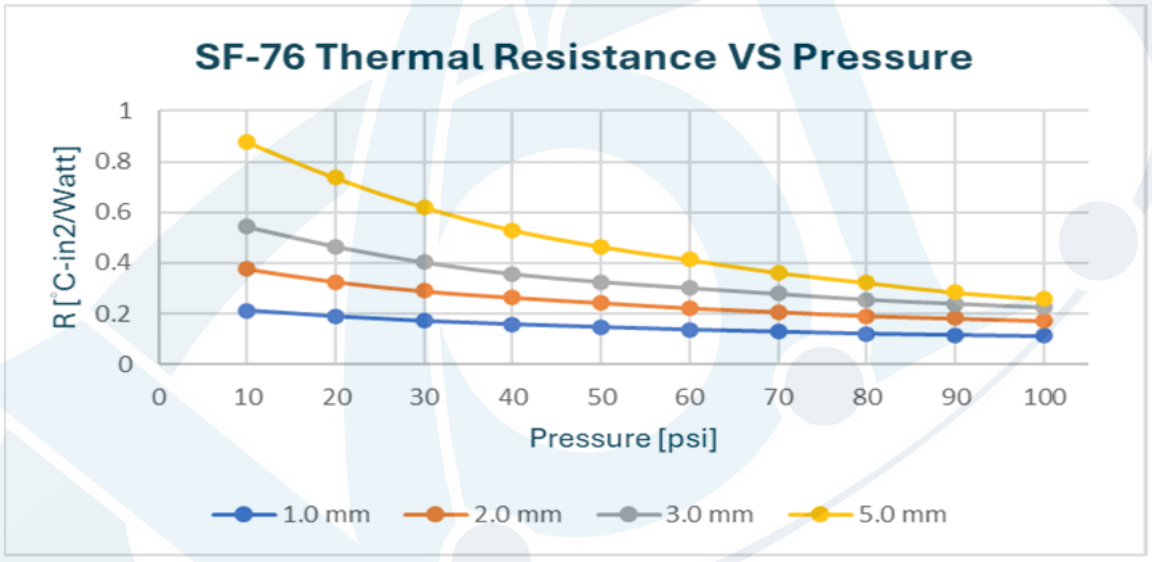

SF-	76	-	xxxxxx	-	xxx
non-silicone	6W/m.K		size 200200=20*20 254254=25.4*25.4		Thickness 005=0.5mm 010=1.0mm